US00D593511S

(12) **United States Design Patent**
Deng et al.

(10) **Patent No.: US D593,511 S**
(45) **Date of Patent: ** Jun. 2, 2009**

---

(54) **HEAT DISSIPATION DEVICE**

(75) Inventors: **Hong-Bo Deng**, Shenzhen (CN); **Di-Qiong Zhao**, Shenzhen (CN); **Ye Chen**, Shenzhen (CN)

(73) Assignee: **Foxconn Technology Co., Ltd.**, Tu-Cheng, Taipei Hsien (TW)

(**) Term: **14 Years**

(21) Appl. No.: **29/321,527**

(22) Filed: **Jul. 18, 2008**

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/179**
(58) **Field of Classification Search** D13/179; 165/80.3, 104.33, 151, 122, 185; 257/706, 257/707, 718–722; 361/687, 695, 697, 700, 361/702, 704, 709, 710, 711, 719
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D511,327 S	*	11/2005	Ma et al.	D13/179
D552,564 S	*	10/2007	Mochizuki	D13/179
D561,123 S	*	2/2008	Mochizuki et al.	D13/179
D561,711 S	*	2/2008	Lin	D13/179
7,362,573 B2	*	4/2008	Lu et al.	361/695
D573,109 S	*	7/2008	Mochizuki et al.	D13/179
2006/0219386 A1	*	10/2006	Hsia et al.	165/80.3

* cited by examiner

Primary Examiner—Selina Sikder
(74) *Attorney, Agent, or Firm*—Frank R. Niranjan

(57) **CLAIM**

The ornamental design for a heat dissipation device, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a heat dissipation device showing our new design.

FIG. **2** is a front elevational view thereof.

FIG. **3** is a rear elevational view thereof.

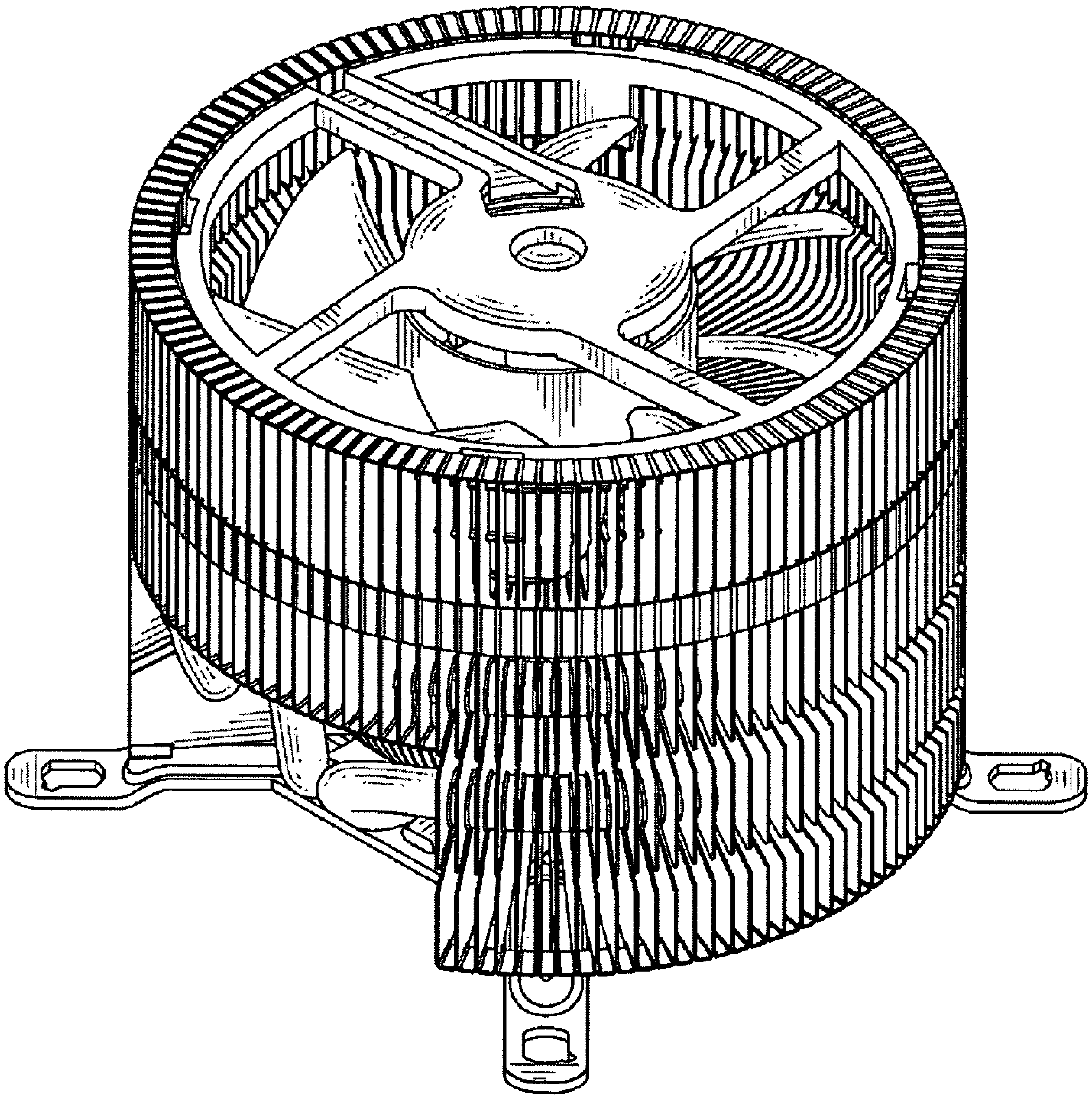
FIG. **4** is a left-side, elevational view thereof.

FIG. **5** is a right-side, elevational view thereof.

FIG. **6** is a top plan view thereof; and,

FIG. **7** is a bottom plan view thereof, wherein the features shown in broken lines are for illustrative purposes only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



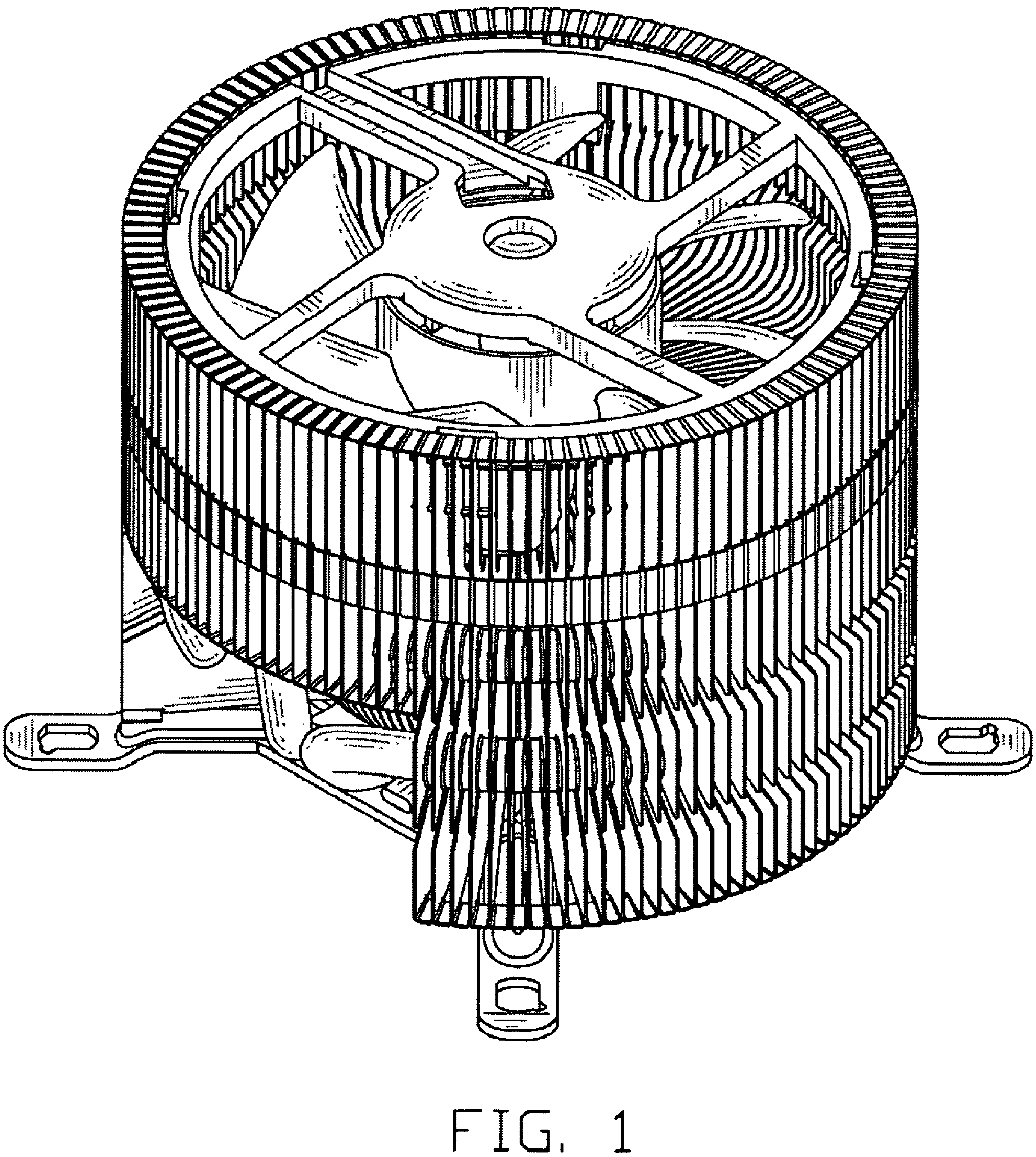


FIG. 1

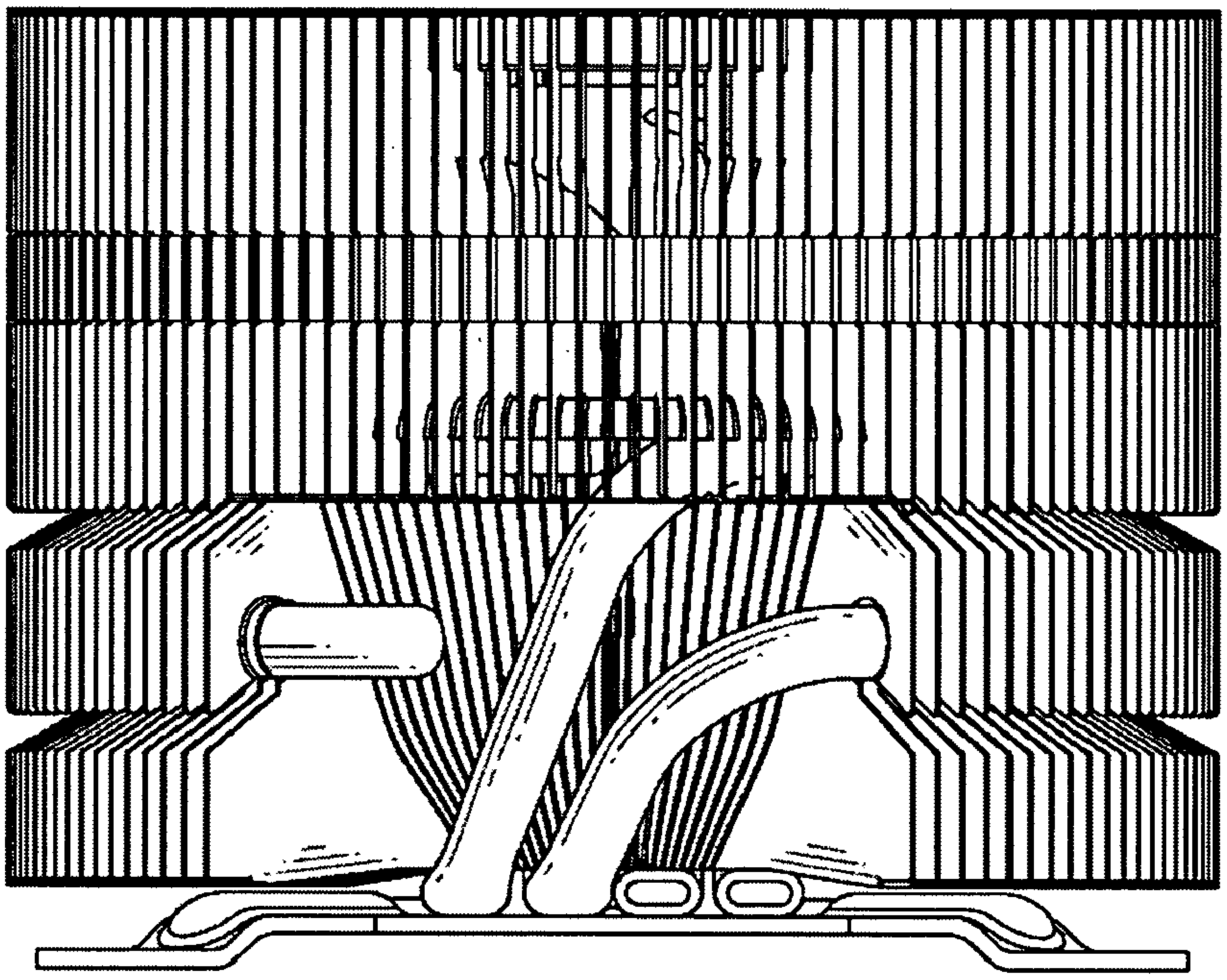


FIG. 2

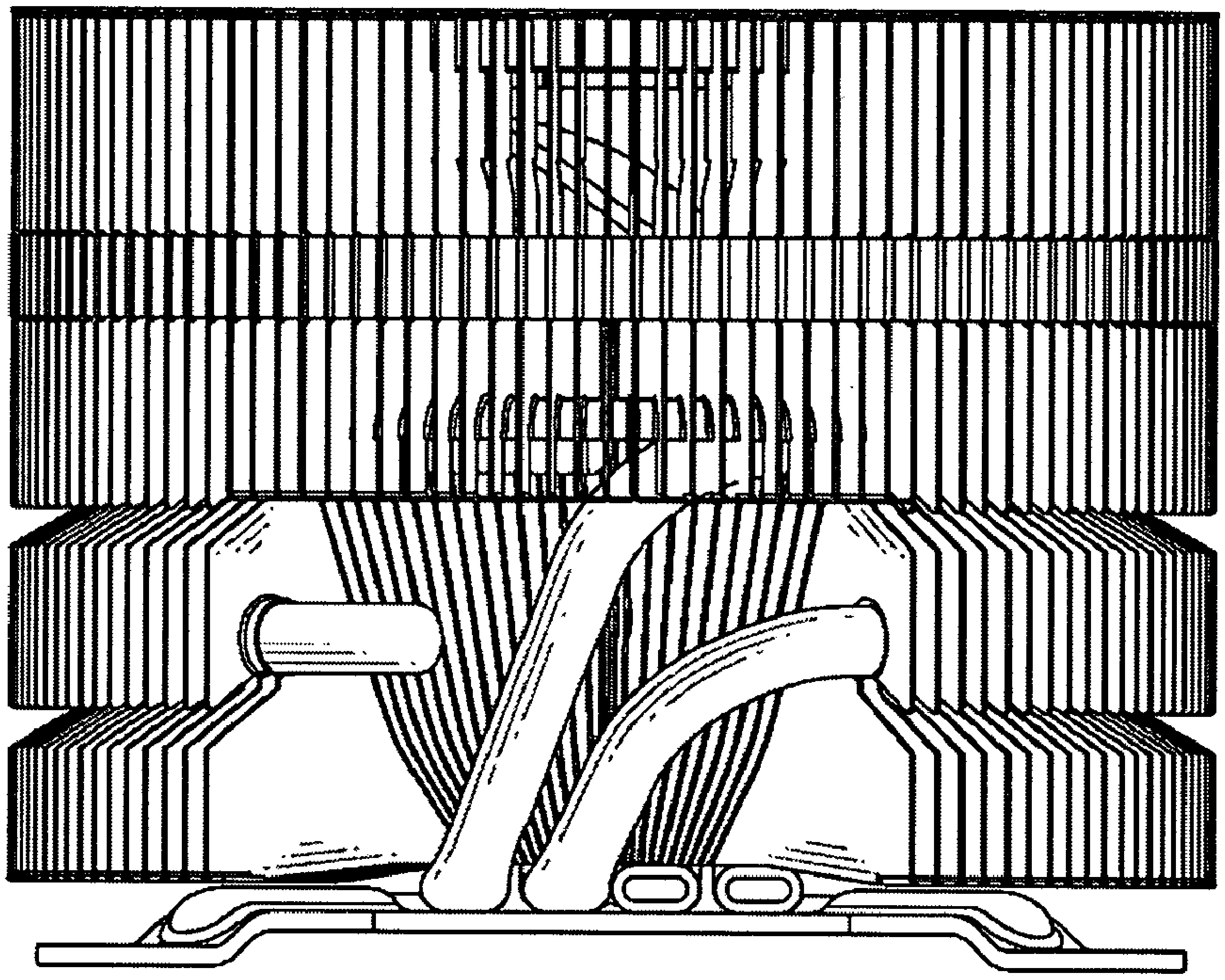


FIG. 3

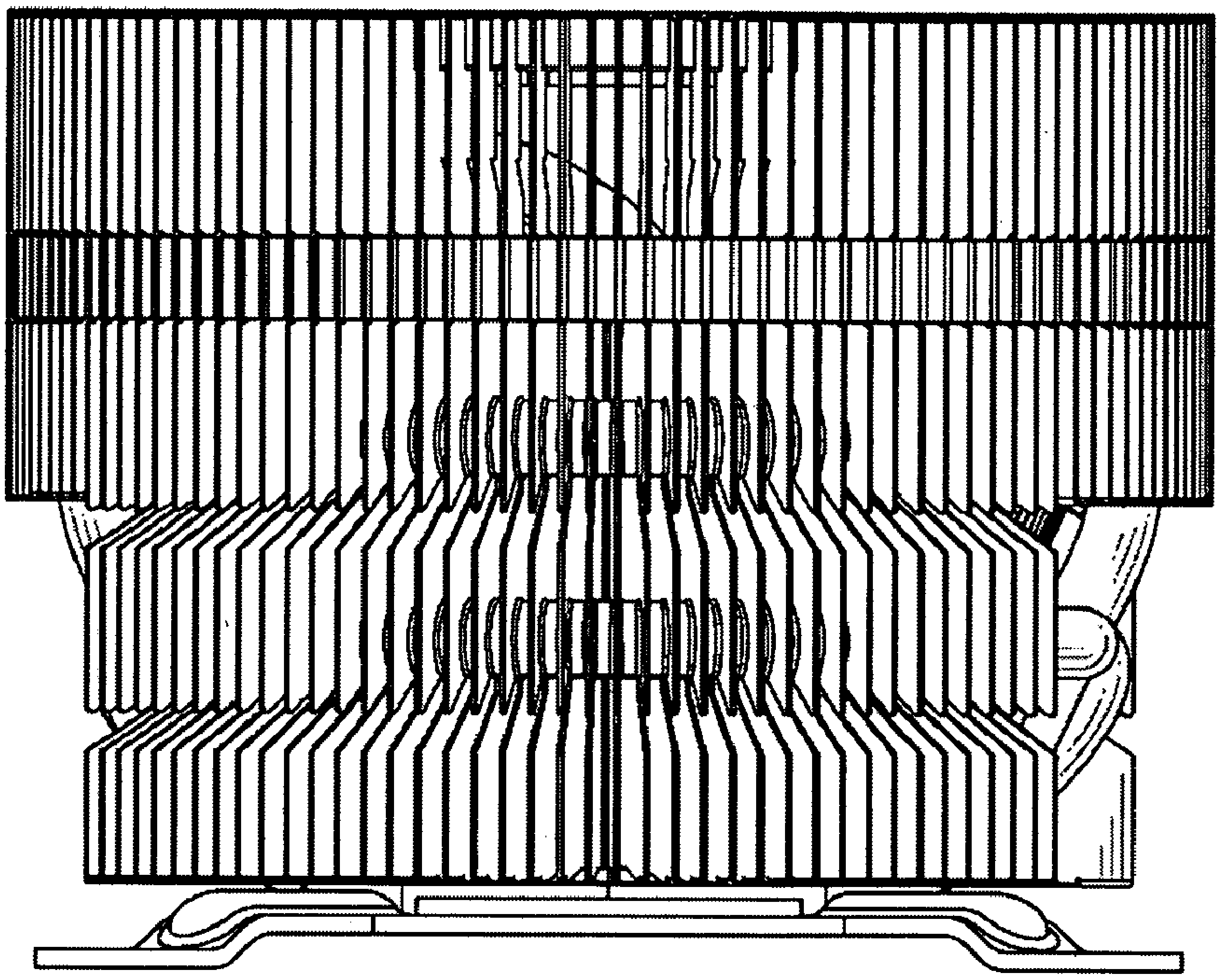


FIG. 4

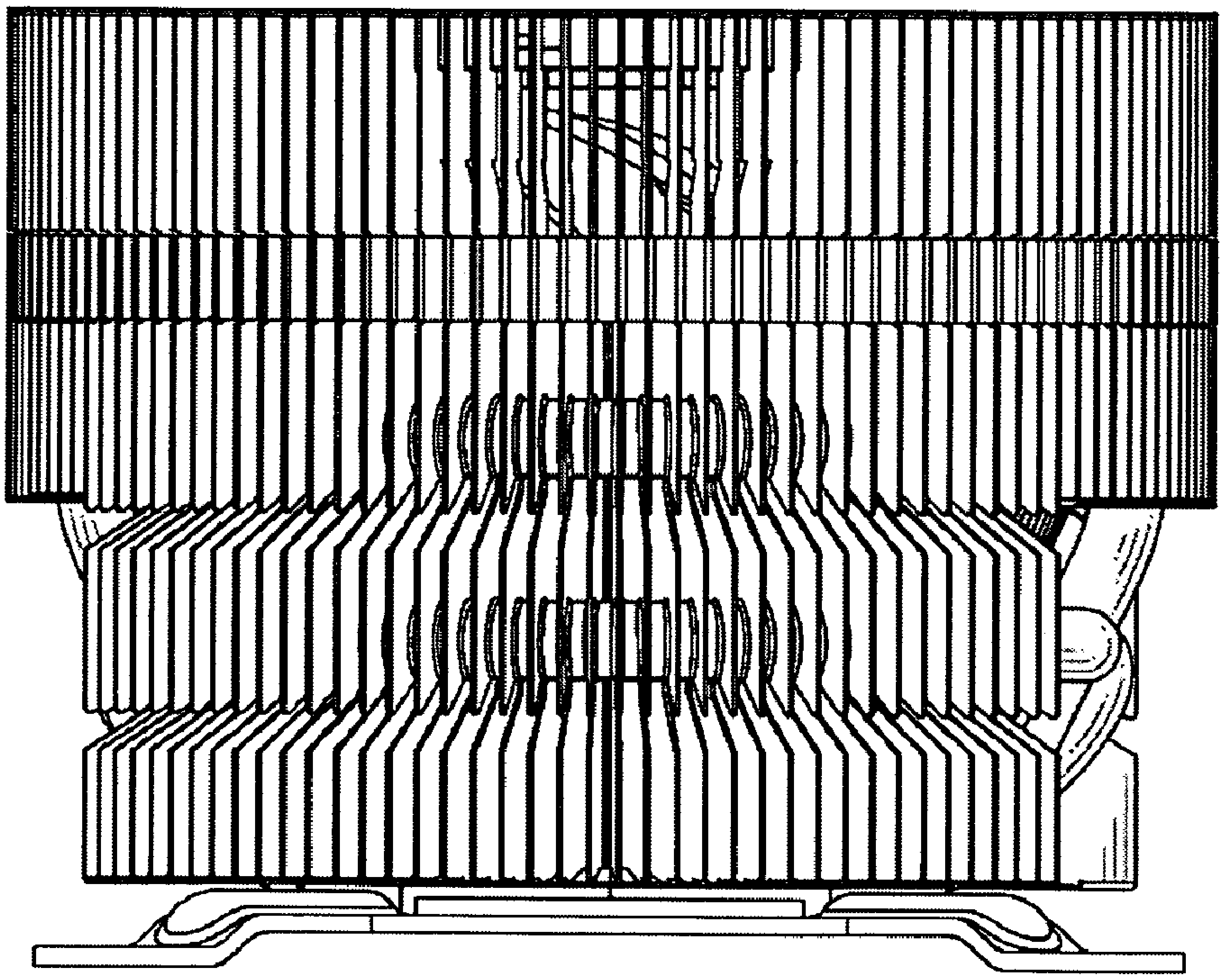


FIG. 5

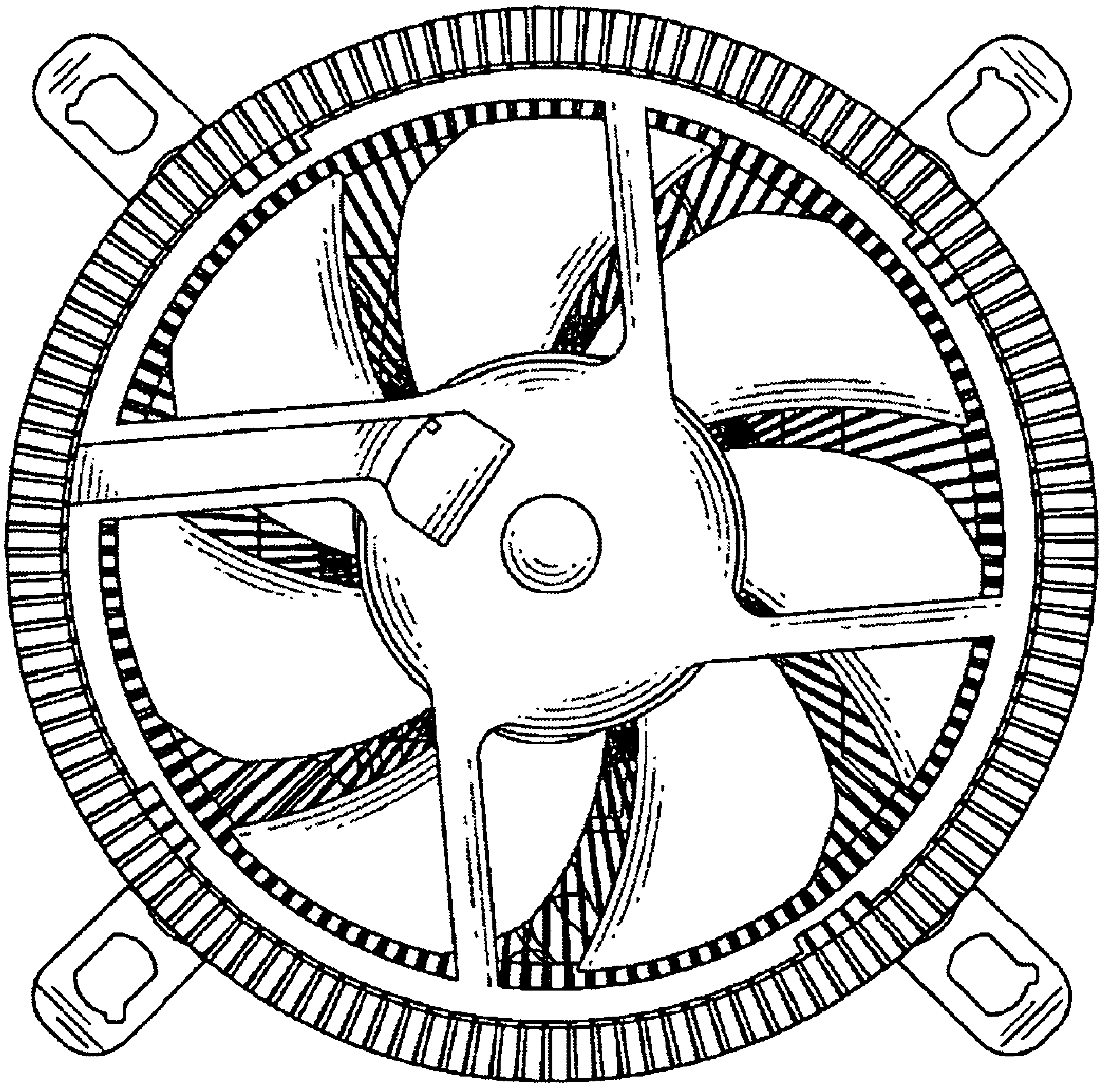


FIG. 6

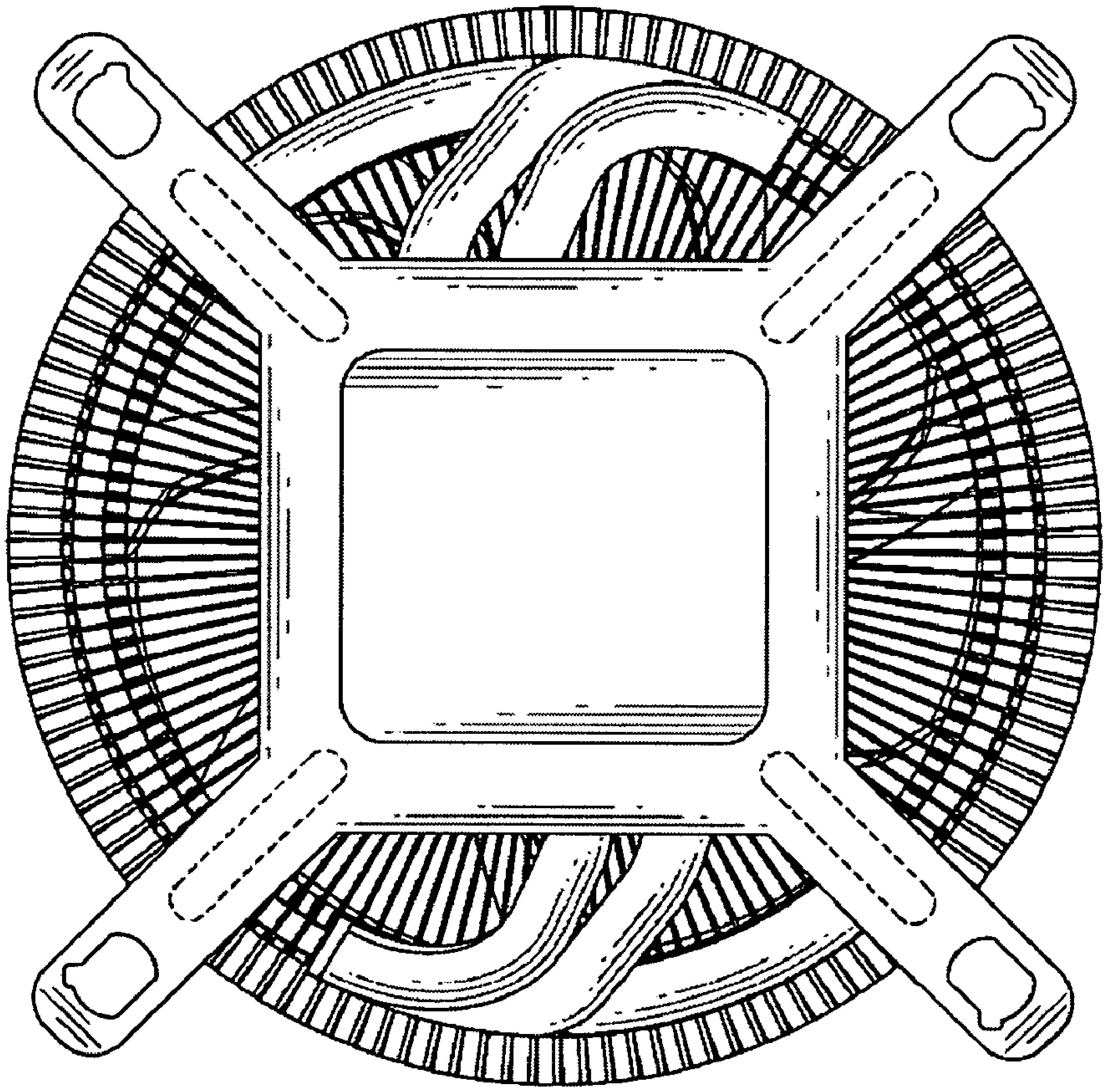


FIG. 7